

SOD-323

FEATURES

- For surface mounted applications
- Fast reverse recovery time
- Ideal for automated placement

MECHANICAL DATA

- Case: SOD-323
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 16mg/0. 00056oz

Absolute Maximum Ratings at 25 °C

Parameter	Symbols	1N4448WS	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Average Rectified Forward Current	$I_{F(AV)}$	250	mA
Non-reptitive Peak Forward Surge Current at 8.3 ms	I_{FSM}	2.0	A
Total Power Dissipation	P_{tot}	500	mW
Typical Thermal Resistance (1)	$R_{\theta JA}$	250	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

(1) P.C.B. mounted with 5*5mm copper pad areas.

Characteristics at $T_a = 25\text{ °C}$

Parameter	Symbols	1N4448WS	Units
Reverse Breakdown Voltage at $I_R=10\text{ }\mu\text{A}$	$V_{(BR)R}$	75	V
Maximum Forward Voltage at 1 m A at 10 m A at 100 m A at 150 m A	V_F	0.715 0.855 1.00 1.25	V
Peak Reverse Current at $V_R=20\text{V}$ $T_j=25\text{°C}$ at $V_R=75\text{V}$ $T_j=25\text{°C}$ at $V_R=25\text{V}$ $T_j=150\text{°C}$ at $V_R=75\text{V}$ $T_j=150\text{°C}$	I_R	0.025 1 30 50	μA
Typical Junction Capacitance $f=1\text{MHz}, V_R=0\text{V}$	C_j	2	pF
Maximum Reverse Recovery Time (2)	t_{rr}	4	ns

(2) Measured with $I_F=I_R=10\text{mA}$, $I_{rr}=0.1 \times I_R$, $R_L=100\Omega$

Typical Characteristics

Fig.1 Power Derating Curve

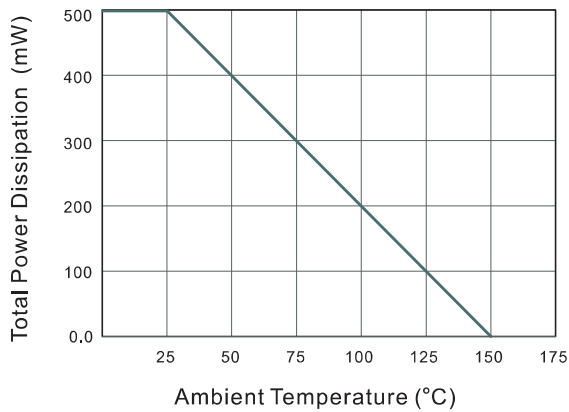


Fig.2 Typical Reverse Characteristics

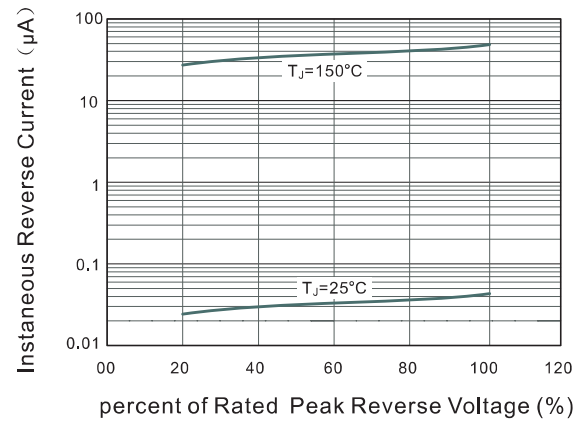


Fig.3 Typical Instantaneous Forward Characteristics

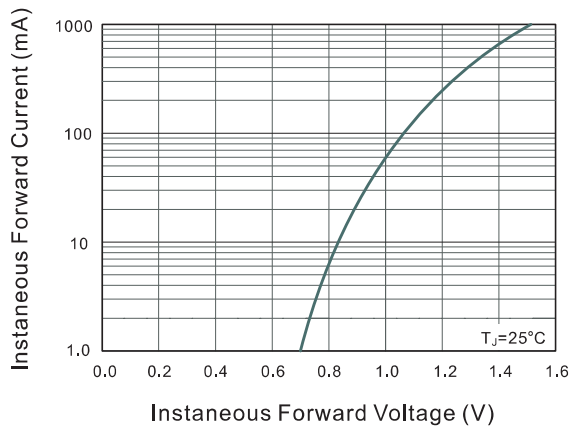
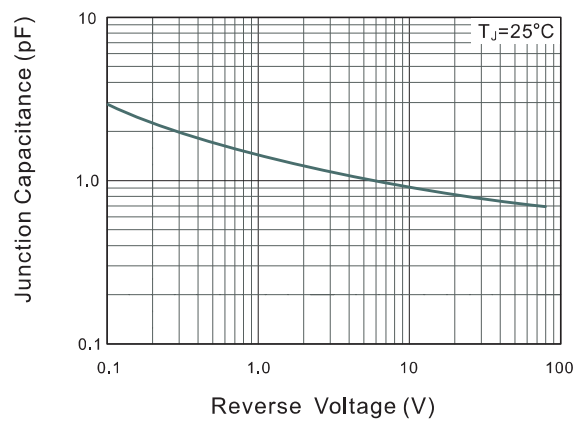
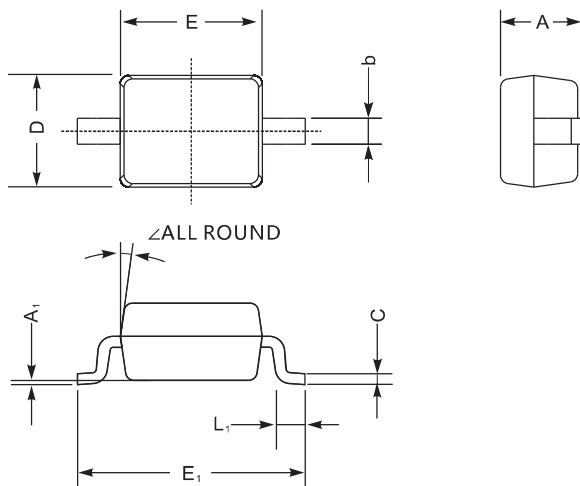


Fig.4 Typical Junction Capacitance

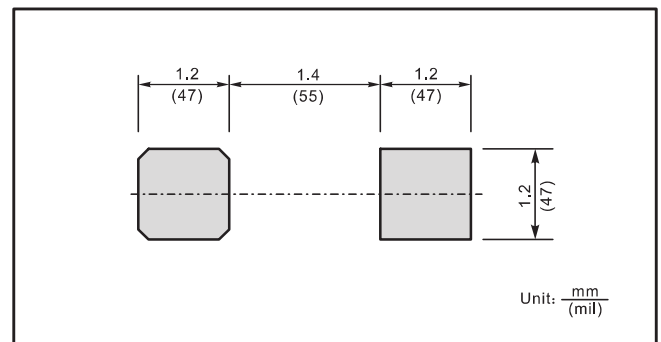


PACKAGE OUTLINE

Plastic surface mounted package; 2 leads



The recommended mounting pad size



Marking

Type number	Marking code
1N4448WS	T5

SOD-323 mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	